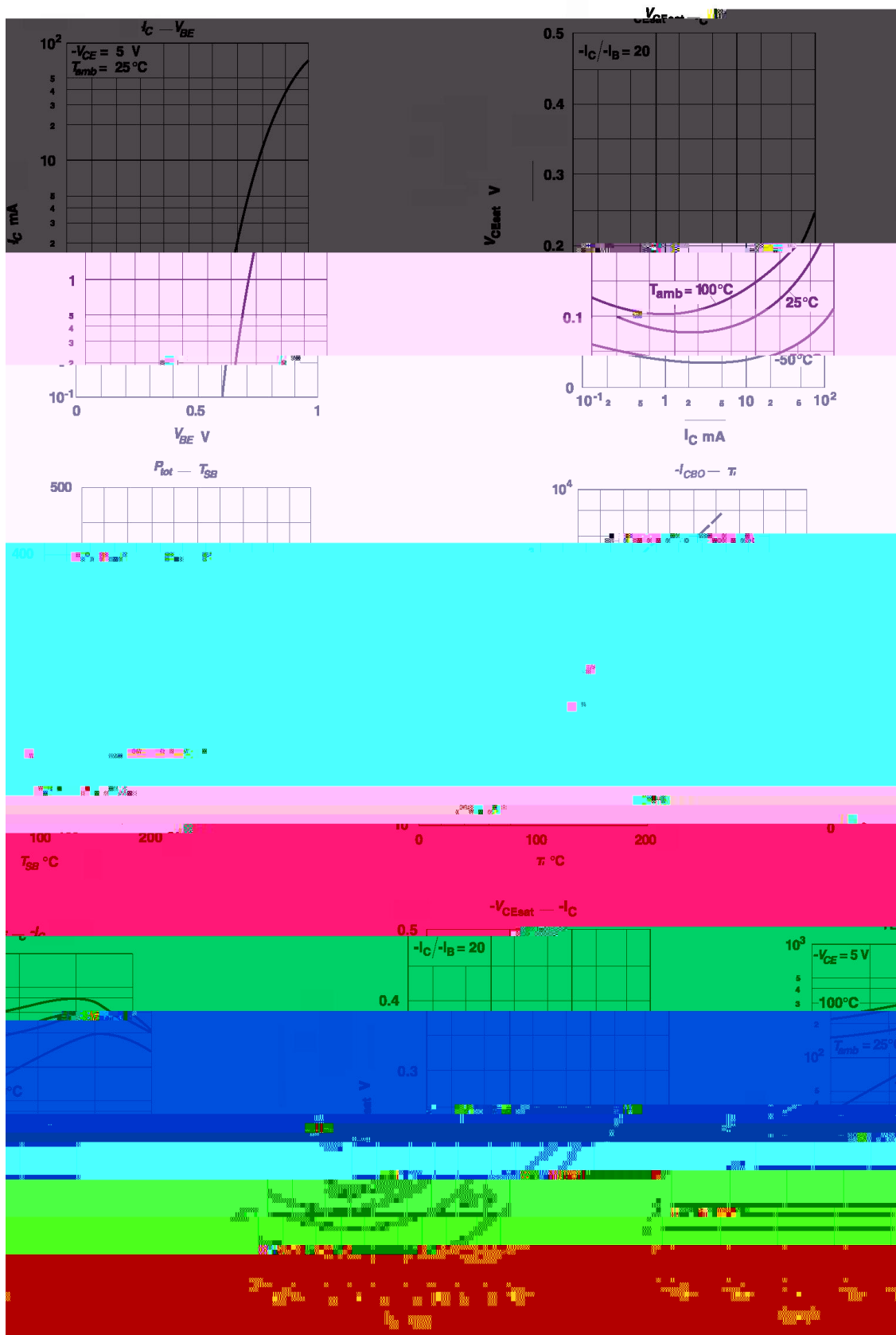
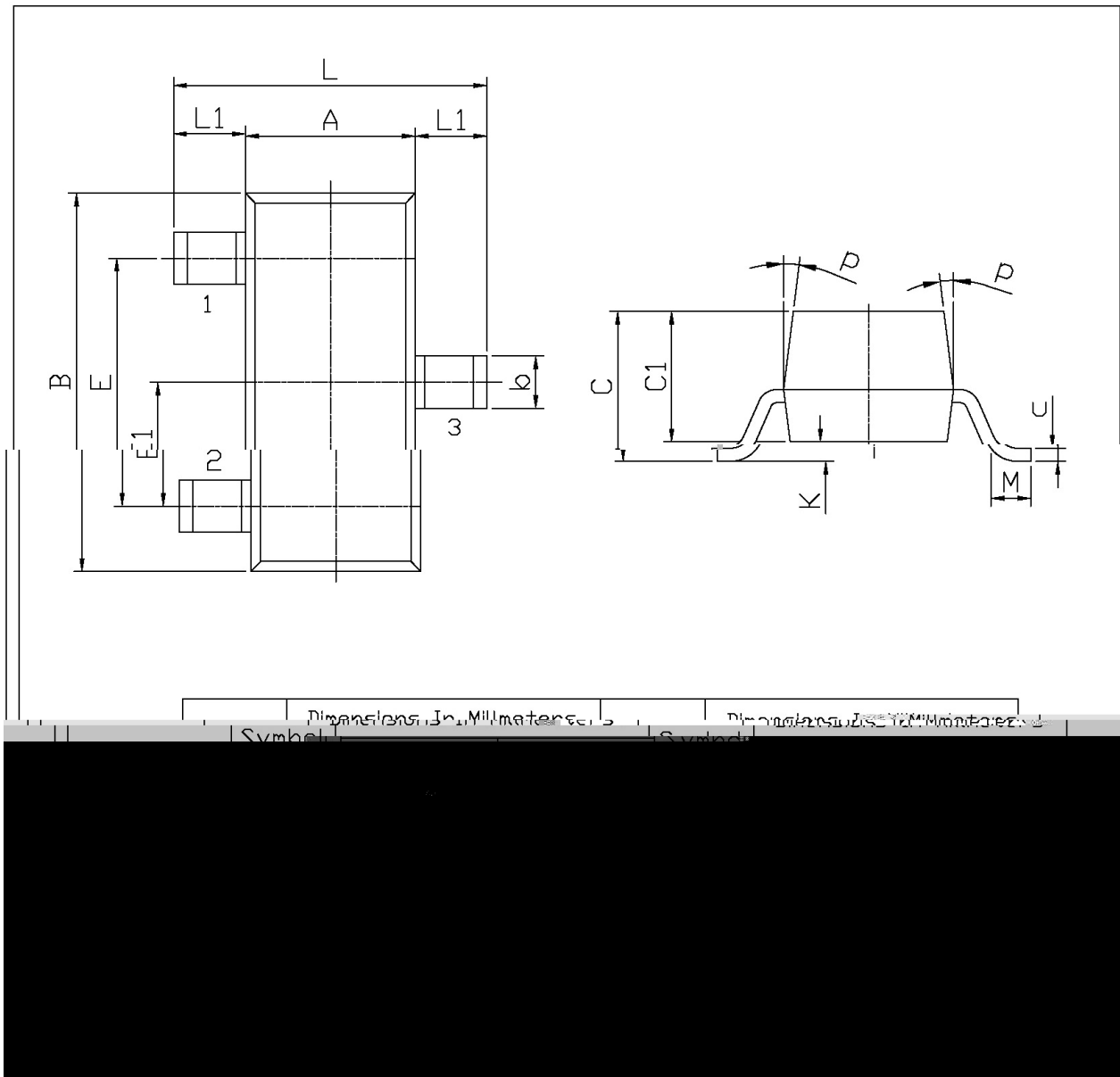
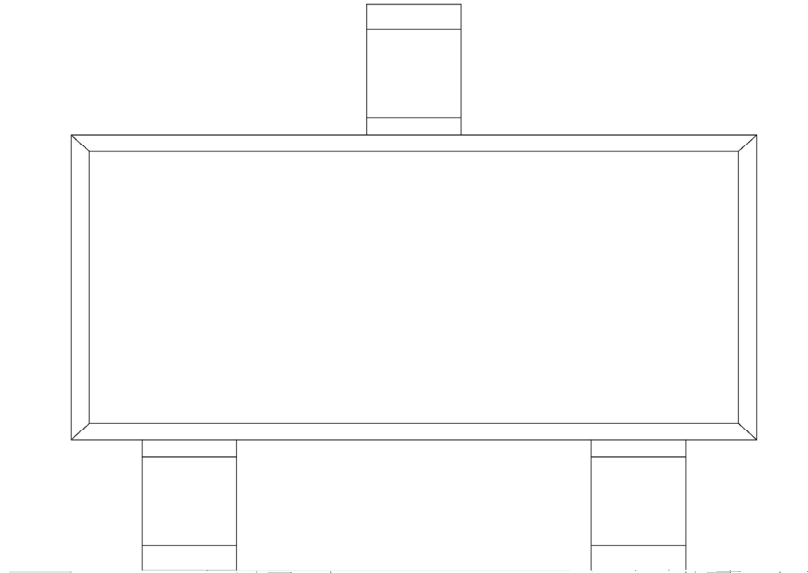


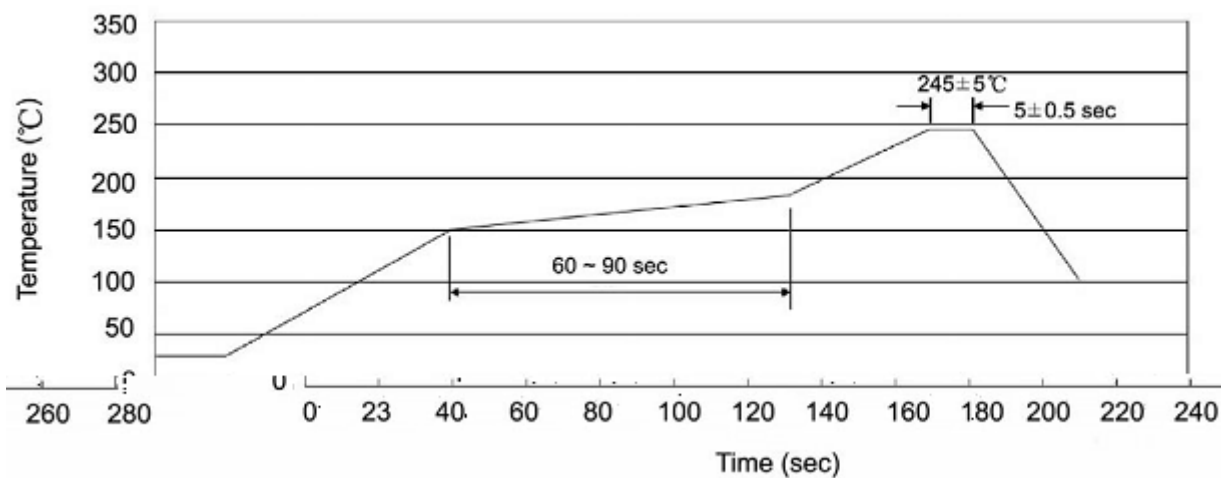
						μ
		Ω				







Temperature Profile for IR Reflow Soldering(Pb-Free)



封装形式	包装数量					包装尺寸 :		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	8	180,000	7 ×8	180×120×180	390×385×205